



Docket No. IRV1.PAU.53

Patent Application

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Pepe, et al.

Serial No.: 09/938,686

Filed: October 30, 2001

For: STACKABLE LAYERS  
CONTAINING ENCAPSULATED  
INTEGRATED CIRCUIT CHIPS  
WITH ONE OR MORE  
OVERLYING INTERCONNECT  
LAYERS AND A METHOD OF  
MAKING THE SAME

Examiner: Hung K. Vu

Group Art Unit: 2811

Irvine, California

May 15, 2003

*# 10/11/03 HKA  
Amended  
5/27/03*

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**AMENDMENT "B" – RESPONSE TO OFFICE ACTION**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Please enter the following amendment in response to the Office Action dated December 19, 2002. A request for a two-month extension of time and appropriate fees are enclosed. If necessary, please charge Deposit Account No. 01-1960.

**IN THE TITLE**

Please amend the title by replacing the title with the following: METHOD OF MAKING STACKABLE LAYERS CONTAINING ENCAPSULATED INTEGRATED CIRCUIT CHIPS WITH ONE OR MORE OVERLAYING INTERCONNECT LAYERS.